DECLARATION FOR PATENT APPLICATION AND APPOINTMENT OF ATTORNEY

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name; I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention (Design, if applicable) entitled: Method for Testing Memories with Seamless Data Input/Output by Interleaving Seamless Bank Commands

the specification of which (check one).

☒ is attached hereto.

❑ was filed on: as Application Serial No.:
    and (if applicable) was amended on.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above. I acknowledge the duty to disclose information which is material to patentability as defined in *Title 37, Code of Federal Regulations, § 1.56.* I hereby claim foreign priority benefits under *Title 35, United States Code § 119* of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

PRIOR FOREIGN APPLICATION(S)			*PRIORITY CLAIMED*	
Number	*Country*	*Day/Month/Year Filed*	*Yes*	*No*
089127914	Taiwan, R.O.C.	27/12/2000	X	

I hereby claim the benefit under *Title 35, United States Code, § 120* of any United States application(s) or PCT international application(s) designating The United States of America listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in that/those prior application(s) in the manner provided by the first paragraph of *Title 35, United States Code, § 112*, I acknowledge the duty to disclose information which is material to patentability as defined in *Title 37, Code of Federal Regulations, § 1.56* which became available between the filing date of the prior application(s) and the national or PCT international filing date of this application:

Application Number	*Filing Date*	*Status - Patented, Pending or Abandonded*

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under *section 1001 of title 18 of the United States Code* and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: I(We) hereby appoint as my(our) attorneys, with full powers of substitution and revocation, to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

Thomas E. Sisson 29348; Mark H. Miller 29197;
Daniel D. Chapman 32726; William B. Nash 33743

I(We) authorize my(our) attorneys to accept and follow instructions from **TAI E INTERNATIONAL PATENT & LAW OFFICE** regarding any matter related to the preparation, examination, grant and maintenance of this application, any continuation, continuation-in-part or divisional based thereon, and any patent resulting therefrom, until I(We) or my(our) assigns withdraw this authorization in writing.

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❑ See following pages for additional joint inventors.